

**Amendments to the Claims**

Please amend the claims as follows.

1. (Currently Amended) A semiconductor device comprising:
  - a semiconductor chip, which produces heat when operated;
  - ~~a pair of heat conducting plates plate for conducting heat from opposite surfaces of the provided on one side of the semiconductor chip, wherein the plates face each other;~~
  - ~~a pair of an insulating sheets sheet, which are is compressively deformable, adhered to the heat conducting plates also provided on the one side of the semiconductor chip; and~~
  - a resin molding covering the semiconductor chip, the plates plate, and the sheets sheet such that the sheets sheet ~~are is~~ exposed from the resin molding.

2. (Currently Amended) The semiconductor device of claim 1, wherein the heat conductivity of the insulating sheets sheet is greater than that of the resin molding.

3. (Currently Amended) The semiconductor device of claim 2, wherein the insulating sheets ~~are~~ sheet is made of silicone rubber.

4-6 (Canceled)

7. (Currently Amended) The semiconductor device of claim 1, wherein the insulating sheets ~~are~~ sheet is adhered to the heat sinks conducting plate using a coating resin applied to ~~the surfaces of the heat sinks~~ heat conducting plate.

8. (Original) The semiconductor device of claim 7, wherein the coating resin is polyamide resin.

9. (Currently Amended) The semiconductor device of claim 1, wherein the semiconductor chip forms part of a stack, and the stack includes the plates plate, and opposite sides of the semiconductor chip are soldered to members of the stack.

10-16. (Canceled)